



As/Intw

Attorney Docket no: 0553-0193.01

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Takayama et al.

Serial No.: 10/672,521

Filed: September 26, 2003

For: Wiring Material, Semiconductor Device
Provided With A Wiring Using The Wiring
Material And Method of Manufacturing
Thereof

Examiner: Ha T. Nguyen

Art Unit: 2812

Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

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Shannon Wallace

Name of applicant, assignee, or Registered Rep.
Shannon Wallace 11/9/05
Signature Date

RESPONSE (C) AFTER FINAL

Applicants have the following response to the Final Rejection of August 9, 2005. Applicants will address each of the Examiner's rejections in the order in which they appear in the Final Rejection.

Claim Rejections - 35 USC §103

Claims 26-28 and 30

In the Final Rejection, the Examiner rejects Claims 29-30 and 32-35 [sic Claims 26-28, 30, 31 and 35] under 35 USC §103(a) as being unpatentable over Matsuda (US 6,078,071) in view of Oikawa et al. (US 4,619,695). This rejection is respectfully traversed.

In particular, independent Claim 26 is directed to a method of manufacturing a wiring in a